

## ABSTRACT

A heat resistant photosensitive resin composition having excellent film properties is provided by  
5 constituting a photosensitive resin composition containing  
(A) a polymer having an acid functional group and/or a substituent derived therefrom, (B) a compound having at least one substituent derived from an amine functional group, (C) a photoreactive compound, and (D) a solvent.  
10 Using this composition, a pattern with high resolution can be produced, and thus an electronic part having a high quality can be produced.